## **APPLICATION DATA SHEET**

Electronic Version v14

Stylesheet Version v14.0

Title of Invention | MIII TI

MULTI-SUBSTRATE CIRCUIT ASSEMBLY

Application Type : regular, utility
Attorney Docket Number : DP-311231

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all	
business in the United States Patent and Trademark Office connected therewith.	
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